

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings of claims in the application:

LISTING OF CLAIMS:

Claims 1-12 (cancelled)

13. (new) A mold conditioning sheet comprising at least two base sheets, a mold conditioning component and a molding member, the mold conditioning component and the molding member being enclosed between the two base sheets; characterized in that the base sheets have a structure in which the base sheets include a fibrous base sheet having a porosity of 70% or more as an outermost layer of the mold conditioning sheet, and the molding member is unvulcanized synthetic rubber and/or natural rubber, does not contain a vulcanizing agent and is heat melted during molding of said mold conditioning sheet.

14. (new) A mold conditioning sheet comprising at least two base sheets, a mold conditioning component and a molding member, the mold conditioning component and the molding member being enclosed between the two base sheets; characterized in that the base sheets have a structure in which the base sheets include a fibrous base sheet having a porosity of 70% or more as an upper side layer or an outermost layer of the mold conditioning sheet and a fibrous base sheet having a porosity of 40% or less and/or a heat-resistant film as a lower side layer of the mold conditioning sheet, and the molding member is unvulcanized synthetic rubber and/or natural rubber, does not contain a vulcanizing agent and is heat melted during molding of said mold conditioning sheet.

15. (new) The mold conditioning sheet according to claim 14, which is used to condition a mold die for single-sided encapsulation of a substrate, etc.

16. (new) The mold conditioning sheet according to claim 13, wherein the mold conditioning component mainly comprises a thermosetting resin and a release agent and contains at least one member selected from a mineral powder and a curing agent.

17. (new) The mold conditioning sheet according to claim 13, wherein a combination of the mold conditioning component and the molding member is enclosed by covering or heat sealing a part, or the whole, of the base sheets using a thermoplastic resin film or tape.

18. (new) The mold conditioning sheet according to claim 13, wherein a combination of the mold conditioning component and the molding member is enclosed by adhering the base sheets using at least one of a double-sided tape, an adhesive, and a pressure sensitive adhesive.

19. (new) The mold conditioning sheet according to claim 13, wherein a combination of the mold conditioning component and the molding member is enclosed by adhering the base sheets by pressing or deforming the base sheets.

20. (new) A method of conditioning a mold die comprising the steps of sandwiching a mold conditioning sheet according to claim 13 between two halves of a heated mold die, applying heat and pressure to the mold conditioning sheet for a given time to cure the mold conditioning component, and removing the mold conditioning sheet.

21. (new) The method of conditioning a mold die according to claim 20, which is carried out after the mold die is cleaned.